

Symbol	Count	Hole Size	Hole Length	Plated	Hole Tolerance (+)	Hole Tolerance (-)	Hole Tolerance	Hole Type
A	75	7.87mil (0.200mm)	-	PTH				Round
☆	863	8.00mil (0.203mm)	-	PTH	3.00mil (0.076mm)	3.00mil (0.076mm)	+/-3.00mil	Round
⊕	55	12.00mil (0.305mm)	-	PTH	3.00mil (0.076mm)	3.00mil (0.076mm)	+/-3.00mil	Round
⊗	2	25.59mil (0.650mm)	29.53mil (0.750mm)	PTH				Slot
⊙	10	31.50mil (0.800mm)	-	PTH				Round
▽	18	32.00mil (0.813mm)	-	NPTH	3.00mil (0.076mm)	3.00mil (0.076mm)	+/-3.00mil	Round
○	20	35.43mil (0.900mm)	-	PTH				Round
▣	3	40.00mil (1.016mm)	-	PTH				Round
▽	23	40.16mil (1.020mm)	-	PTH				Round
□	6	45.28mil (1.150mm)	-	NPTH	3.00mil (0.076mm)	3.00mil (0.076mm)	+/-3.00mil	Round
⊗	2	51.18mil (1.300mm)	29.53mil (0.750mm)	PTH				Slot
★	4	66.93mil (1.700mm)	-	PTH				Round
◇	3	102.99mil (2.616mm)	-	PTH				Round
B	4	108.00mil (2.743mm)	-	NPTH	3.00mil (0.076mm)	3.00mil (0.076mm)	+/-3.00mil	Round
✕	4	127.95mil (3.250mm)	-	NPTH				Round
✕	2	127.95mil (3.250mm)	-	PTH				Round
⊗	4	159.00mil (4.039mm)	-	NPTH	3.00mil (0.076mm)	3.00mil (0.076mm)	+/-3.00mil	Round
	1098 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

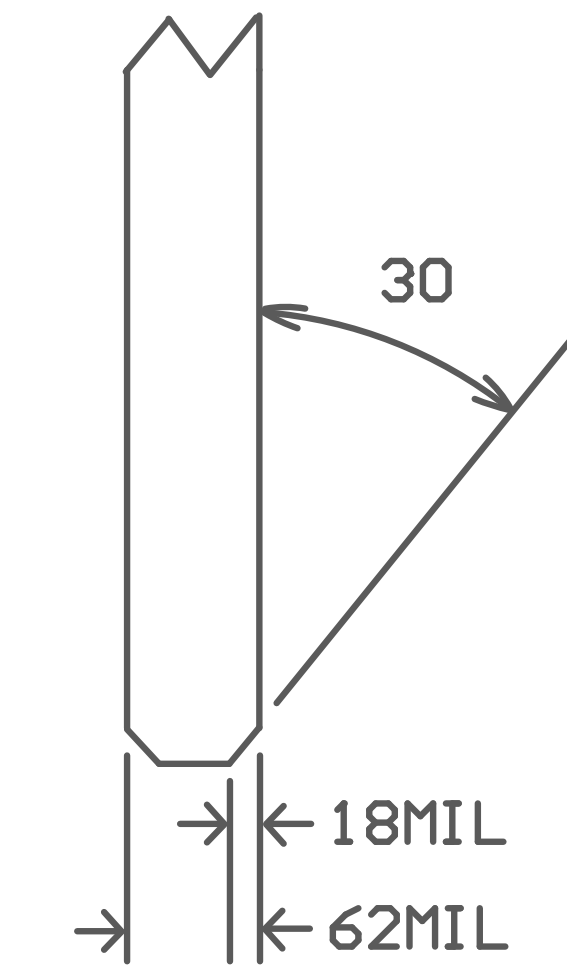
SCALE : NTS

NOTES:

- BOARD SHALL MEET THE REQUIREMENTS OF UL-796E WITH FLAMMABILITY RATING OF MINIMUM 94V-0. UL LOGO, MANUFACTURER'S IDENTIFICATION AND DATE CODE LETTER SHALL BE RENDERED IN SILKSCREEN.
- VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED, PROVIDED NO ADJACENT COPPER IS EXPOSED & NO CONFLICT IS PRODUCED WITH ANY STATED "VIA TENTING/COVERING" REQUIREMENTS.
- MANUFACTURER'S IDENTIFICATION,DATECODE LETTER SHALL BE SILKSCREENED ON SOLDER SIDE OF THE BOARD.
- LAYER TO LAYER REGISTRATION SHALL BE WITHIN +/-2 MIL.
- REFER IMPEDANCE TABLE FOR IMPEDANCE CONTROL TRACES ON LAYER 1, 3 & 6.
- ALL VIAS ARE TENTED ON BOTH SIDES UNLESS OTHERWISE SOLDER MASK OPENED IN GERBER. VIA HOLES SHALL BE FILLED WITH NON CONDUCTIVE INK AND COVERED WITH SOLDER MASK.

IMPEDANCE TABLE : [6]

LAYER	TRACE WIDTH	SPACING	IMPEDANCE +/- 10%	REFERENCE LAYER
TOP	5.66 MILS	-	50 OHM	LAYER-2 (GND LAYER)
BOTTOM	5.66 MILS	-	50 OHM	LAYER-5(GND LAYER)
TOP	4 MILS	7 MILS	100 OHM	LAYER-2 (GND LAYER)
TOP	5 MILS	6.22 MILS	90 OHM	LAYER-2 (GND LAYER)
L3	6.66 MILS	-	50 OHM	LAYER-2 / LAYER-4
L3	4.2 MILS	6 MILS	100 OHM	LAYER-2 / LAYER-4
BOTTOM	4 MILS	7 MILS	100 OHM	LAYER-5(GND LAYER)
BOTTOM	5 MILS	6.22 MILS	90 OHM	LAYER-5(GND LAYER)
L3	5.7 MILS	6 MILS	90 OHM	LAYER-2 / LAYER-4



GOLD FINGER
SIDE VIEW

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	2.00mil	3.6	
1	Top Layer		1.85mil		
	Dielectric 1	FR-4	3.70mil	4.1	
2	GND1		1.26mil		
	Dielectric 2	FR-4	5.00mil	3.7	
3	SIG1		1.26mil		
	Dielectric 3	FR-4	32.00mil	3.7	
4	PWR		1.26mil		
	Dielectric 4	FR-4	5.00mil	3.7	
5	GND2		1.26mil		
	Dielectric 5	FR-4	3.70mil	4.1	
6	Bottom		1.85mil		
	Bottom Solder	Solder Resist	2.00mil	3.6	
	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 4 MIL
MIN. CLEARANCE: 4.5 MIL
MIN. VIA PAD SIZE: 18 MIL
MINIMUM ANNULAR RING 0.127mm (5MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

☐ FR-408☒ FR-4 High Tg☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10%☐ OTHERTOLERANCE:

☒ ANSI IPC-6012 TYPE 3 CLASS 2☐ OTHER +/-

BOW & TWIST:

☒ ANSI IPC-6012 TYPE 3 CLASS 2☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN☒ NC_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE☐ OTHERSOLDER RESIST COLOR: ☒ GREEN☐ OTHER BLUE

☐ MATTE☒ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV☒ OTHER HARD GOLD OVER NICKEL 30u/80u, ON EDGEFINGERS

ARRAY/PANEL:

☐ CUT AND TRIM PER M1 BOARD OUTLINE☒ N.C. ROUTE☐ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1☒ 2☐ 3

☒ RoHS☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBERADDITIONAL REQUIREMENTS:
BARE BOARD ELEC. TEST: ☐ NONE☐ REQUIRED☒ PER ORDER

☐ OUTER LAYERS 6 MIL WIDE, 6 MIL SPACE
TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE
INNER LAYERS 5 MIL WIDE, 7 MIL SPACE
☐ TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE
OUTER LAYERS 6.1 MIL WIDE, 6 MIL SPACE
☐ TRACES REQUIRE 90 OHM DIFFERENTIAL IMPEDANCE

TEXAS
INSTRUMENTS

PROJECT TITLE:
AM261 HSEC Adapter BoardDESIGNED FOR:
Public ReleaseFILE NAME:
PROC200E1.PcbDocENGINEER:

LAYOUT BY:
.PCB_Layout

SCALE: 1.00

ALTUM DESIGNER VERSION:
24.0.1.36

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PROC200	REV: E1	SUN REV: 465
LAYER NAME = <div>PCB Board Outline</div>	TID #:		
PLOT NAME = Fab Drawing	GENERATED : 01/10/2024 12:57:53		TEXAS INSTRUMENTS

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ENGINEER:	LAYOUT BY: .PCB_Layout
SCALE: 1.00	ALTUM DESIGNER VERSION: 24.0.1.36